IPC  ASSOCIATION CONNECTED ELECTRONICS INDUST.	© Copyright 2005. IP	Material Composition Declaration © Copyright 2005. IPC, Bannockburn, Illinois. All rights reserved under both international and Pan-American copyright conventions.			der both This do	This document is a declaration of the substances within the manufacturer listed item. Note: if the item is an assembly with lower level parts, the declaration encompasses all lower level materials for which the manufacturer has engineering responsibility.									
752-21.1		IPC Web Site for Information on IPC-1752 Standard Form Typ http://www.ipc.org/IPC-175x Distribute				Declaration Class * Class 6 - RoHS Yes/No, Homogeneous Mater					ials and Mfg Information				
upplier Info	rmation														
Company name*			Company unique ID			Unique ID	Unique ID Authority					Response Date*			
nsemi												2024-05-04			
Contact Name			Title - Contact			Phone - Co	Phone - Contact*					Email - Contact*			
Product-Env-Ste	wards		Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
uthorized Repro	esentative*		Title - Representative			Phone - Re	Phone - Representative*				Email - Representative*				
Product-Env-Stewards			Product Enviro Compliance			NA	NA				Product-Env-Stewards@onsemi.com				
Reque	ster Item Number			Mfr Item Name		Effective	Date	Version	Manufacturing Site		V	Weight*	UOM	Unit Type	
				50 mA Ultra-Low I Low Dropout Linea	q, Wide Input Voltage ur Voltage Regulator	, 2024-05-0	024-05-04 MY1			9	0.0	mg	Each		
Ianufacturin	g Proccess Informat	ion													
Terminal Plating / Grid Array Material Terminal Base Alloy			Alloy J-S	STD-020 MSL Rating	MSL Rating Peak Process Body Temperature Max Time at Peak Temperature Number of Reflow Cy						eles				
Matte Tin (Sn) - annealed			CU Alloy 1			260	260 C 30		30		second	ds 3			
omments															
vel 1 - maximun	n time at peak temperatu	re during sol	dering is 10-3	30 seconds											
or more informa	ation regarding material o	composition 1	please refer t	o page 3				•		•	•		_		

RoHS Material Composition Declaration			Declaration Type *	Detail	ed				
Directive 2015/863/EU amending RoHS Directive 2011/65/EU		ium (Cr6+), Polybrominated Biphenyls (PB)	erial for Cadmium and quantity limit of 0.1% b B), Polybrominated Diphenyl Ethers (PBDE), a						
cadmium, hexavalentchromium, polybromin contains a RoHS restricted substance inexce encompass all such components. Supplier cet as of the date that Supplier completes this Company acknowledges that Supplier may hindependently verified information provided certification in this paragraph. If the Compan	nated biphenyls and/or polybrominated diphess of an applicable quantity limit, please indriffes that it gathered the information it provom. Supplier acknowledges that Company wave relied on informationprovided by others of the supplier agrees that, at a minimusy and the Supplier enter into a written agree yesource of the Supplier's liability and the C	enyl ethers (each a "RoHS restricted substan licate below which, if any, RoHS exemption vides in this form using appropriate methods vill rely on this certification in determining the s in completing this form, and that Supplier um, itssuppliers have provided certifications ement with respect to the identified part, the tompany's remedies for issues that arise rega	s of the European Union member states) of the ce") in excess of the applicable quantity limit is you believe may apply. If the part is an assemb to ensure its accuracy and that such informatio e compliance of its products with European Ur may not have independently verified such infor regarding their contributions to the part, and the erms and conditions of that agreement, including information the Supplier provides in this	dentified above. If a ally with lower level in is true and correct tion member state la mation. However, in ose certifications are ag any warranty righ	homogeneous material within the part components, the declaration shall to the best of its knowledge and belief, was that implement the RoHS Directive. In situations where Supplier has not the at least as comprehensive as the lats and/or remedies provided as part of				
RoHS Declaration * 1 - Item	(s) does not contain RoHS restricted substar	nces per the definition above	Supplier A	cceptance *	Accepted				
Exemption: If the declared item does not contain RoHS restricted substances per the definition above except for defined RoHS exemptions, then select the corresponding response in the RoHS Declaration above and choose all applicable exemptions.									
Exemption List Version	EL-2011/534/EU								
Declaration Signature									
		e "Accepted" on the Supplier Acceptance	drop-down. This will display the signature a	rea. Digitally sign t	the declaration (if required by the				

## **Homogeneous Material Composition Declaration for Electronic Products**

SubItem Instructions: The presence of any JIG Level A or B substances must be declared. [1] indicate the subpart in which the substance is located, [2] provide a description of the homogeneous material [3], enter the weight of the homogeneous material.

Substance Instructions: [A] select the Level (JIG A, JIG B, Requester or Supplier) [B] select the substance category (JIG or Requester) or enter a value (Supplier). [C] select the substance (JIG) or enter the substance and CAS (Other). [D] select a RoHS exemption, if applicable [E] enter the weight of the substance or the PPM concentration [F] Optionally enter the positive (+) and negative (-) tolerance in percent (Note: percent tolerance values are expected to cover a 3 sigma range of distribution unless otherwise noted).

Homogeneous Material	Weight	Unit of Measure	Level	Substance	CAS	Exempt	Weight 0.7	Unit of Measure
Die	0.7	mg	Supplier	Silicon (Si)	7440-21-3			
Die Attach	0.19	mg	Supplier	Epoxized Condensate Of Para- Hydrobenzaldehyde And Alkyl Phenol	129915-35-1		0.038	mg
			Supplier	Silver (Ag)	7440-22-4		0.152	mg
Lead Frame	3.1	mg	Supplier	Silver (Ag)	7440-22-4		0.031	mg
			Supplier	Tin (Sn)	7440-31-5		0.0077	mg
			Supplier	Zinc (Zn)	7440-66-6		0.0068	mg
			Supplier	Chromium (Cr)	7440-47-3		0.0077	mg
			Supplier	Copper (Cu)	7440-50-8		3.0467	mg
Mold Compound-Black	4.65	mg	Supplier	Epoxy and Phenolic Resin	40216-08-8		0.372	mg
			Supplier	Carbon Black (C)	1333-86-4		0.0233	mg
			Supplier	Aluminum Hydroxide (Al(OH)3)	21645-51-2		0.093	mg
			Supplier	Fused Silica (SiO2)	60676-86-0		4.0223	mg
			Supplier	Phenolic Resin (Novolac)	9003-35-4		0.1395	mg
Plating	0.18	mg	Supplier	Tin (Sn)	7440-31-5		0.18	mg
Wire Bond - Au	0.18	mg	Supplier	Gold (Au)	7440-57-5		0.18	mg